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(57) **ABSTRACT**

A cooling system for a computing device is described. The cooling system includes a heat transfer structure. The heat transfer structure includes a heat spreader, a fin structure, and a differential pressure device. The fin structure transfers heat from the heat spreader to a fluid. The differential pressure device generates a low pressure region that draws the fluid from an ingress in the computing device through the fin structure. The heat transfer structure is enclosed in a chamber of the computing device. The chamber includes the ingress and an egress.

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